



QUALCOMM

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21 October 2013

Mr. Xavier Piednoir and Ms. Susanna Kooistra
3GPP MCC
ETSI
650, route des Lucioles
06921 Sophia-Antipolis Cedex
France

Subject: Nomination for the position of Vice-Chairman of 3GPP TSG CT WG6

Dear Mr. Piednoir and Ms. Kooistra:

QUALCOMM is pleased to nominate Mr. Michele Berionne for the position of vice-chair of 3GPP TSG-CT WG6. Michele Berionne works for QUALCOMM Technologies Inc. and represents QUALCOMM Incorporated, an ATIS member, in 3GPP.

A brief curriculum vitae of Michele Berionne is attached.

Best Regards,

A handwritten signature in black ink, appearing to read 'Edward G. Tiedemann, Jr.', with a stylized flourish at the end.

Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
QUALCOMM Incorporated

Michele Berionne

Michele graduated in 2002 with a Master's degree in Telecommunications Engineering from the Università di Roma "La Sapienza", Italy.

Michele has been working at QUALCOMM since 2006. He initially worked in the IMS development team. Since 2008, he has been leading a software development team for the UICC card module in the chipsets, focusing on interaction between the UICC and other parts of the system. He started attending CT WG6 in January 2011.